

UNIVERSAL Universal Display LTD

SPECIFICATION FOR LCD MODULE

Customer	· . 					
Product Model:		KD035G	<u>6-541</u>	NT-A1		
Sample co	ode:					
Designed by	Ch	ecked by		Approved by		
Final Appro	Final Approval by Customer					
LCM Mac	hinery OK		CM OF	<		
Checked By			lG,Pr	oblem survey:		
LCM Display OK Checked By		Approved E	Ву			

^{**}The specification of "TBD" should refer to the measured value of sample . If there is difference between the design specification and measured value, we naturally shall negotiate and agree to solution with customer.

Revision History

Version	Contents	Date	Note
Α	Original	2010.01.06	
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<u> </u>			
 			

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1 Numbering System

(1)	(2)	(3) (4)	(5)	(6)	(7)	(8)

No	Definition	Specifications
(1)	TFT LCM Productor No.	KD
(2)	Display monitor opposite angle line size	Unit :mm or mmm (size <10 inch: takes two integers; size >=10 inch: takes three integers)
(3)	Productor Types	D Digital photo frame / DVD GGPS MMP PMobil-Phone
(4)	Productor Development Series No.	By two figures characters expression from 01 to 99
(5)	Interface PIN Number	By two figures characters expression from 01 to 99
(6)	With Touch Panel Or Not	TWith T/P; NWithout T/P
(7)	LCD Type	AAUO; MCMO; CCPT; PPVI; LLG; WWintek; HHSD; TTopply; YHydis; IHitach; SSharp。。
(8)	Productor Development edition No.	By The English litters : A 1~ Z9
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2 Scope

It is capable of using 262k colors mode 24bit parallel bi-directional interface.

3 Normative Reference

GB/T4619-1996 《 Liquid Crystal Display Test Method》

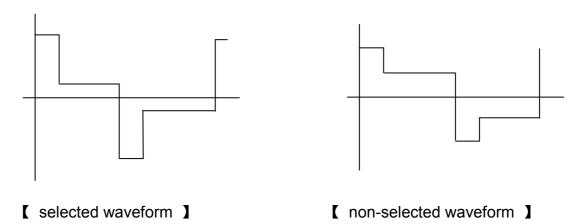
GB/T2424 《Basic environmental Testing Procedures for Electric and Electronic Products.》

GB/T2423 《Basic Testing Procedures for Electric and Electronic Products》 IEC61747-1 《SIXTH PARTGB2828`2829-87《National Standard of PRC》

4 Definitions

4.1 Definitions of Vop

The definitions of threshold voltage Vth1, Vth2 the following typical waveforms are applied on liquid crystal by the method of equalized voltage for each duty and bias.



① Vth1: The voltage which the brightness of segment indicates 50% of saturated value on the conditions of selected waveform (f_f =80Hz, Φ =10° θ =270° at 25°C)

② Vth2: The voltage which the brightness of segment indicates 50% of saturated value on the conditions of non-selected waveform $(f_f=80\text{Hz},\ \Phi=10^\circ\ \theta=270^\circ\ \text{at }25^\circ\text{C})$

③ Vop: (Vth1(50%)+Vth2(50%))/2 $(f_f=80Hz, \Phi=10^{\circ} \theta=270^{\circ} at 25^{\circ}C)$

4.2 Definition of Response Time Tr, Td

①Tr: The time required which the brightness of segment becomes 10% from 100% when waveform is switched to selected one from non-selected one. (f_f =80Hz, Φ =10° θ =270°at 25°C)

2)Td: The time required which the brightness of segment

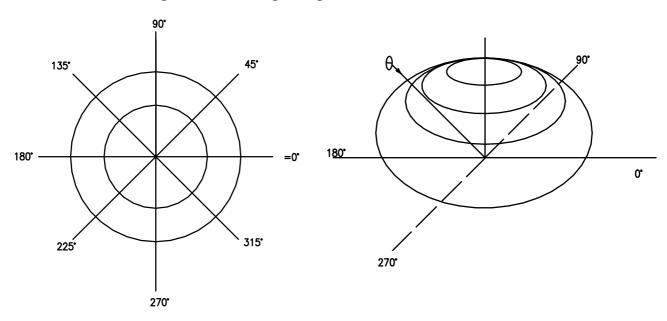
becomes 90% from 10% when waveform is switched to selected one from selected one. (f_f=80Hz, Φ =10° θ =270°at 25°C)

4.3 Definition of Contrast Ratio Cr

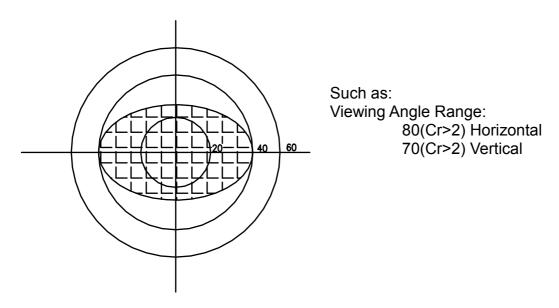
Cr=A/B

- ① A: Segments brightness in case of non-selected waveform
- ② B: Segments brightness in case of selected waveform

4.4 Definition of Angle and Viewing Range



Angular Graph: Constrast Ratio



5 Technology Specifications

5.1 Feature

This single-display module is suitable for use in Multidedia Player products.

The LCD adopts one backlight with High brightness 6-lamps white LED.

- 1) Construction: 3.5" a -Si color TFT-LCD, White LED backlight, FPC.
- 2) LCD:
 - 2.1 Amorphous-TFT 3.5-inch display, transmissive, normally white type.
 - 2.2 320(RGB)×240dots Matrix.
 - 2.3 Narrow-contact ledge technique.
 - 2.4 LCD Driver IC: NT39016D \times 1.
- 3) Low cross talk by frame rate modulation.
- 4) 262K Color ,24bit RGB interface.
- 5) Video signal interface: Parallel RGB.

5.2 Mechanical Specifications

0.2 McChamca opcomoations							
Item	Specifications	Unit					
Dimensional outline	76.9(W) ×63.9(H)×3.2 (T)	mm					
TP outline		mm					
TP(V.A)		mm					
TP(A.A)		mm					
Active area	70.08(W) ×52.56 (H)	mm					
Pixel size	219(W) ×219(H)	um					
Resolution	320(RGB) × 240	pixel					
Luminance	310 (TYP)	cd/m ²					

5.3 Absolute Max. Rating

5.3 Absolute Max. Rating

Item	Symbol	Value			Unit	Remark	
Item		Min	typ	Max	Offic	Remark	
Supply voltage	VDD	-0.3	3.3	5.0	V	-	
Operating temperature	T _{OPR}	-20	-	+70	$^{\circ}\!\mathbb{C}$	-	
Storage temperature	T _{STG}	-30	-	+80	$^{\circ}\!\mathbb{C}$	-	

5.4 Electrical Characteristics

DC Electrical Characteristics

DC Electrical Characteristics

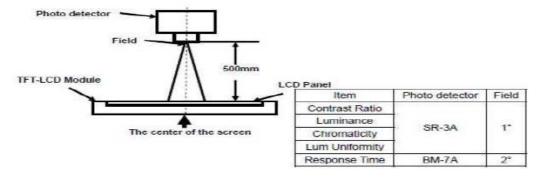
(For the digital circuit: Test Condition: VDD=VDDP=3.3V, VDDA=5.0V, GND=GNDA=GNDP= 0V, TA=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Digital Block Circuit						
Digital Supply Voltage	VDD	3.0	3.3	3.6	Mr	Oigital power
Low Level Input Voltage	Vil	GND	S((-))	0,2000	٧	Digital input pins TA=85°C
High Level Input Voltage	Vih	₀ 0.8x V(DD		_\overline{\bullet}	(V	Digital input pins TA=85°C
Low Level Input Voltage	_vi(\/	GND	<i>J</i> -	0.2xVDD	_W_	Digital input pins TA=25°C
High Level Input Voltage	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	0.8xVDD	11:	(YBO)	JV	Digital input pins TA=25℃
Low Level Input Voltage	VIE	GND	16.11	\0\4x\0DD	٧	Digital input pins TA= -20°C
High Level Input Voltage	Vih	0.9xVDD		VDD	٧	Digital input pins TA= -20℃
Input Leakage Current	\I(11 11	-	±1	μА	Digital input pins
Pull-high/low Impedance	Rin	<i>J</i> J - ~	200K	-	ohm	Digital control input pins
High Level Output Voltage	Voh	VDD-0.4	-	VDD	٧	Digital output pins; loh = 400 uA
Low Level Output Voltage	Vol	GND		GND+0.4	٧	Digital output pins; Iol = -400 uA
Digital Stand-by Current	lddst		(50)	(100)	uA	No load, CLKIN/VSD/HSD stopped
Digital Operating Current	ldd1	-	2	-	mΑ	CLKIN = 27 MHz (CCIR601mode)
Power Circuit						
Charge Pump Supply Voltage	VDDP	3.0	3.3	3.6	٧	For VGH/VGL power and Source Driver power, must in this rang
VCOMAC output level	VCOMAC	4.6	-	6.1	٧	By VCSL[2:0] setting VCOMAC = V(vcsL[2:0]) +- 100mV
VCOMDC output level	VCOMDC	1.0	-	2.26	٧	By VCDCSL[5:0] setting VCOMDC = V _(VCDCSL[5:0]) +- 50mV
Positive power supply	VGH	14.5	15	15.5	٧	Gate driver load + procard load
Negative power supply	VGL	-9	-10	-11	٧	Gate driver load + procard load
Base drive current	IDRV	-	-	10	mΑ	VDDP=3.3V, DRV=0.7 V
DRV output voltage	VDRV	GND +0.1	-	VDD -0.1	٧	
Feed back voltage	VFB	0.55	0.6	0.65	٧	DC/DC operating, VBL current=20 m/
					_	

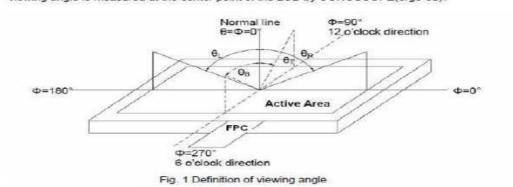
5.5 Optical specifications

Item		Symbol	Condition	Min	Typ.	Max.	Unit
		θТ		30	40	-	
View Angles		9B	CR≥10	50	60	-	Dograd
View Arigies		θL	CR = 10	50	60	-	Degree
		θR]	50	60	-	
Contrast Ratio		CR	θ=0°	200	350	-	
Response Tim		Ton	25℃	_	25	40	ms
Response Till	0	Toff	25 C		25	4	IIIS
	White	×		0.260	0.310	0.360	
	vviiite	У	Backlight is on	0.283	0.333	0.383	
	RED	×		0.574	0.624	0.674	
Chromaticity		У		0.318	0.368	0.418	
Chilomaticity	GREEN :	×		0.300	0.350	0.400	
		У		0.500	0.550	0.600	
	BLUE	×		0.093	0.143	0.193	
	BEUE	У		0.069	0.119	0.169	
Uniformity		U		75	80	-	%
NTSC				-	50	-	%
Luminance		L		240	300	-	cd/m²

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system. viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



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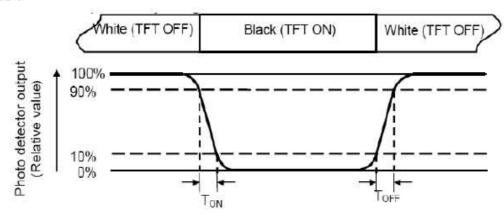
Note 3: Definition of contrast ratio

 $\mbox{Contrast ratio (CR)} = \frac{\mbox{Luminance measured when LCD is on the "White" state}}{\mbox{Luminance measured when LCD is on the "Black" state}}$

Vwhite: To be determined Volack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



5.6 LED back light specification (6 White Chips)

Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	Vf	lf=20mA	-	19.2	-	V
Uniformity (with L/G)	ΔB _p	lf=20mA	80	-	-	%
Luminance for LCD	L _V	If=20mA		3600	-	cd/m ²

LED CIRCUIT



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[&]quot;White state ": The state is that the LCD is driven by Vwhite.

[&]quot;Black state": The state is that the LCD is driven by Volack

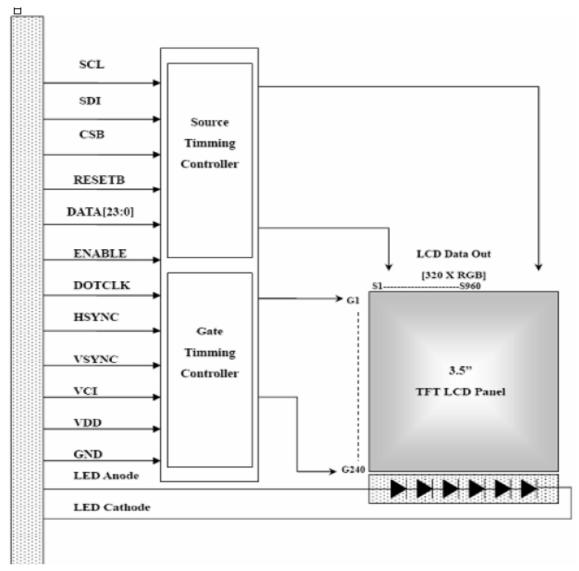
5.7 Interface Pin Connections

PIN NO.	Symbol	Description
1-2	LED-K	LED Cathode(-)
3-4	LED-A	LED Cathode(+)
5	NC	Non Connection
6	NC	Non Connection
7	NC	Non Connection
8	/RESET	Reset
9	CS	Serial data enable
10	SCK	Serial clock
11	SDI	Serial data
12-19	B0- B7	Blue Data 0-7
20-27	G0- G7	Green Data 0-7
28-35	R0- R7	Red Data 0-7
36	HSYNC	Horizontal sync
37	VSYNC	√ertical sync
38	DCLK	Dot(data) Colck
39-40	AVDD	NC
41-42	VDD	Power Supply(3.3V)
43	NC	Non Connection
44-45	VGL	NC
46	NC	Non Connection
47	VGH	NC

48	NC(XR)	Non Connection
49	NC(YD)	Non Connection
50	NC(XL)	Non Connection
51	NC(YU)	Non Connection
52	ENB	Data Enable signal
53	GND	GND
54	GND	GND

6 Signal timing diagram and Circuit block diagram

6.1 Circuit block diagram



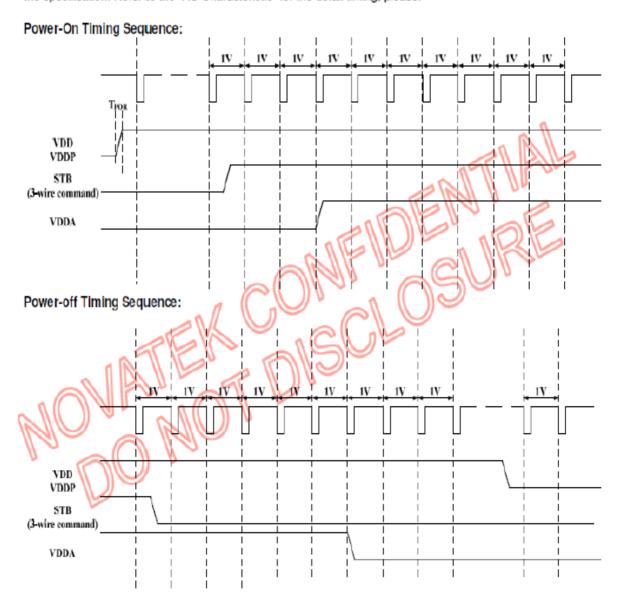
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6.2 Signal Timing Diagram

6.2.1 Power ON Sequence

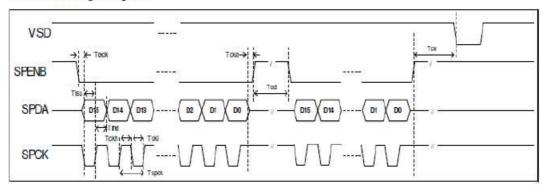
Power On/Off Sequence

To prevent IC from power on reset fail, the rising time (T_{POR}) of digital power supply VDD, should be control within the specification. Refer to the "AC Characteristic" for the detail timing, please.



6.2.2Serial mode timing &clock

3-Wire Timing Diagram



Serial clock	Tspck	320	100	×	ns	
SPCK pulse duty	Tscdut	40	50	60	%	
Serial data setup time	Tisu	120			ns	
Serial data hold time	Tihd	120	180	ē.	ns	
Serial clock high/low	Tssw	120	120	- 0	ns	
Chip select distinguish	Tod	1	120	*	US	
SPENA to VSD	Tov	1			us	

6.2.3 Serial Transmission mode

3-Wire Serial Port Interface (Default Register Map)

3-Wire Command Format

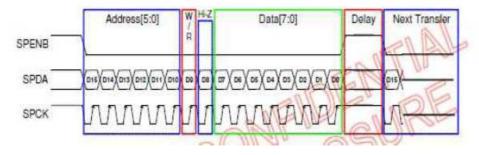
NT39016 uses the 3-wire serial port as communication interface for all the function and parameter setting.

3-Wire communication can be bi-directional controlled by the "RW" bit in address field. NT39016 3-Wire engine act as a "slave mode" for all the time, and will not issue any command to the 3-Wire bus itself.

Under read mode, 3-Wire engine will return the data during "Data phase". The returned data should be latched at the rising edge of SPCK by external controller. Data in the "Hi-Z phase" will be ignored by 3-Wire engine during write operation, and should be ignored during read operation also. During read operation, external controller

should float SPDA pin under "Hi-Z phase" and "Data phase".

Refer to the section of "3-Wire Timing Diagram" for the detail timing, please.



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3-Wire Command Format:

Bit	Description
D15-D10	Register Address [5:0].
D9	W/R control bit. 1" for Write: 0" for Read
D8	H-Z bit during read mode. Any data within this bits will be ignored during write mode
D7-00	Data for the W/R operation to the address indicated by Address phase

3-Wire Writer Format:

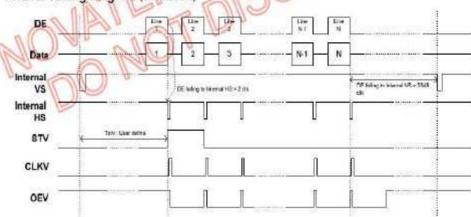
MSB		-11	11	N		,	u .	v	4	v= =	,	v =			LSB
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Register Address [5:0]				1	Х		D	ATA (Is	sue by e	external	control	er)			

3-Wire Read Format:

MSB	MSB LSB														
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
Register Address [5:0]				0	Hi-Z	DATA (Issue by NT39016)					0				

6.2.3 DEMode Timing

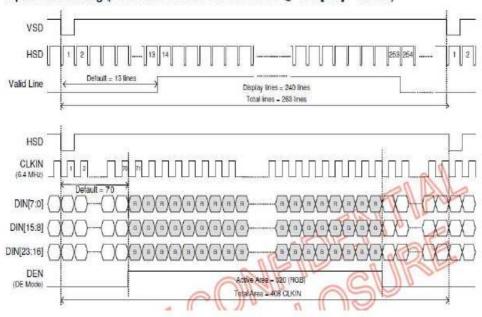




CLKIN clock time	Tolk	100		35.7	ns	CLKIN = 28MHz
HSD to CLKIN	Tho	8	*	1	CLKIN	
HSD width	Thwh	1	(8)	- 54	CLKIN	. 0
VSD width	Tvwh	1	(*)	2.5	Th	1 M
HSD period time	Th	60	63,56	67	us	200
VSD setup time	Tvst	12	-	+	ns	0
VSD hold time	Tvhd	12		. %	ns	
HSD setup time	That	12	1.0	12	ns	The second
HSD hold time	Thhd	12	-	255	ns	000
Data set-up time	Tdsu	12	- 0	1115	ns	DIN[23:0] to CTKIN
Data hold time	Tdhd	12	0	SAID	ns /	DIN[23 0] to CLKIN
DENseuptime	Tesd	12/		1	ns	DEN to CLKIN

6.2.4 24bit RGB Interface Timing

Input Data Timing (24 bit RGB mode for 960 x 240 @ SEL[3:0] = 1100b)



24 Bit RGB Mode (@ SEL[3:0] = 1100 or 1101)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
CLKIN frequency	Fclk	1081	6.4		MHz	VDD = 3.0 ~3.6V
CLKIN cycle time	Tclk	•	156		ns	
CLKIN pulse duty	Tcwh	40	50	60	%	Tclk
Time from HSD to VCOMOUT	Thycm		30	*	CLKIN	
Time from HSD to DATSEQ	Thseq	1	20	2	CLKIN	
Time from HSD to Gate output n line	Thgz		. 5	*	CLKIN	
Time from HSD to Gate output n+1 line	Thgo		45	*	CLKIN	
Time that HSD to 1'st data input(NTSC)	Ths	40	70	255	CLKIN	DDLY =70, Offset = 0 (fixed)

7 Initial code

8 AC Chatacteristics

Test Condition: (VDD=VDDP=3.3V, VDDA=5.0V, GND=GNDA=GNDP=0V, TA= 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
System Operation Timing			01	y y		
VDD power source slew time	T _{POR}			1000	US	From OV to 90% VDD
RSTB active pulse width	T _{RSTB}	40			US	VDD = 3.3V

9 Reliability Test Conditions And Methods

NO	Item	Condition	Method
1	High / Low Temperature Storage	80℃/-30℃ 120hrs	Check and record every 48Hrs
2	High / Low Temperature Life	70°C/-20°C 120hrs (operating mode)	Check and record every 48Hrs
3	High Temperature、 High Humidity Operating	60°C,90% RH, 96Hrs	Check and record every 48hrs
4	Thermal Shock	-30°C(30Min) → 25°C(5Min)	Each 10 cycles end , check
5	Vibration	10Hz~55Hz~10Hz Amplitude: 1.5mm 2hrs for each direction(X,Y,Z)	Each direction end, Check the Appearance and Electrical Characteristics
6	Static Electricity	Gap mood: ±1KV~±8KV (10 times air discharge with positive/negative voltage voltage gap : 1kv) Touch mood: ±1KV~±4KV	Each discharge end, Check the Electrical Characteristics

7	Curve	60 Thousand times, 40 times/min 150° (according to die if exist)	Check and record every 2~4 thousand times
8	Slump	Free faller movement for each side cording angle (75cm High 6 sides 2 angle 2 cording)	End

10. Inspection standard

No	Item		Criterion									
01	Outline Dimension	In a	In accord with drawing									
02	Position-fin ding Dimension Assemble Dimension	In a	In accord with drawing									
03	LCD black spots, white spots (Round type)	Round type: non displace 3.1 Small area LCD	Unit : mm Dimension D≤0.1 0.1 <d≤0.15 d="">0.15</d≤0.15>	Qualified Quantity Ignore 2 0								

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		3.2Large area	a I CD					
			<u> </u>	D	imension		Qualifi Quant	
		$\rightarrow x \leftarrow -$	Y		D≤0.1		Ignor	
			•	0.1	<d≪0.15< td=""><td></td><td colspan="2">2</td></d≪0.15<>		2	
				0.1	5 <d≤0.20< td=""><td></td><td>1</td><td></td></d≤0.20<>		1	
					D>0.20		0	
		C-STN : if D>0	.1 , und	qualifi	ed			
		Unit : mm	4.	1	Small	á	area	LCD
				gth	Width		Qualified Quantity	
		w	-		≤0.015		Igno	
		≤1.	.0	0.015 <w< td=""><td>\</td><td>2</td><td></td></w<>	\	2		
				.0	0.025		1	
				.0	0.025 <w< 0.05</w< 	\	1	
			-	D>0.05			According to circle	
04	LCD black spots, white spots		4.2	2Larg	e area LCD			·
	(Line Style)	→	Leng	gth	Width		Qual Qua	
		→	-		≤0.015		Igno	
		$\left \begin{array}{c} \longleftarrow \\ \bot \end{array}\right $	₹2	.0	0.015 <w 0.025</w 	\leq	2	
			≤1.	.0	0.025 <w< 0.05</w< 	\leq	1	
			-		D>0.05		Accord	
				CS	TN : If W ≽ Ignore be			

	LCD Scratch 、	Same to NO.3 circle	e ce of LCD is vertical					
05	Threadlike	(2)Same to NO.3 lin						
06	POL	else, unqualified. It is essential that frame, else, unqua	e that POL is beyond the edge of glass, POL is over the 50 percent of width of lified. awing in case of special definition.					
		Scratch	Reject					
07	IC/FPC Bonding	Intensity Of Adhesion	If lower than specification, reject					
		Gold Fold Twist	Reject					
07	IC/FPC Bonding	Silicon	According to outline, no gold outside, seal can not be higher than LCD					
		FPC Gold Sever	Reject					
		Lack of Component Polarity Inverse	If exist, reject					
		Leak Solder、 Virtual Solder	If exist, reject					
08	SMT	Short Circuit In Solder Point	If exist, reject					
	51	Tin Ball	If exist, reject					
		Tin Acumination	If visual, reject					
		Height Solder Point	If higher 0.5mm than component. reject					

	T		<u> </u>		
		Height of component	Either side higher 0.5mm than component, reject		
		Component Shift	X<3/4Z reject y>1/3D reject		
	SMT	Few Tin	PCB pad		
08		Component Deflection	Component Pad If Y >1/3D reject		
		Component Carcass Sideways	If Y >1/3D reject Reject		
@ A II	Rights Reserved		21/26 RFV A		

		Component Carcass Sideways	If exist with visual inspection , reject		
		A: Tin accrete the solder side completely, hollowly,Ok B: Tin accrete the solder side completely, full circle arc, ok C: Jointing include whole solder side, height of tin>50 percent of height of component, reject			
		Few Tin	A: Tin accrete the solder side completely , hollowly ,Ok B: height of tin > 1/3 of solder side of component , ok C: height of tin ≤ 1/3 of solder side of component, reject		
08	SMT	Normal Jointing side			
	Light	Short circuit \ Open circuit	Forbid		
09		Quality of CSTN Display	1. Rolling strake with visual inspection, forbid 2. Differentness of color in viewing area with visual inspection (full white, red, green, blue), forbid 3. Display change with visual inspection, forbid		

				<u> </u>		
10		white	±0.05	±0.05		
				±0.05	Drive LCD under normal	
	Color Of CIE Coordinate	Red	±0.05		condition, 25° C Φ =0 Θ =0	
		Green	±0.05	±0.05	Test white red green blue	
		Blue	±0.05	±0.05	with DMS Record	
		According to the specification or sample customer have approved				
11	Brightness	In accord with product specification		Drive condition is according to specification Measure location is in Follow Picture 3. Adjust brightness instrument tozero, burrow against the surface of LCD, press "measure", record when the display is steady. (YOKOGAWA-3298)		
					Measure location	
12	CR (Max)	According to specification			ng to product specification re instrument (DMS-501)	
13	Response time	According to specification			ng to product specification re instrument (DMS-501)	
14	Viewing angle	According to specification			ng to product specification re instrument (DMS-501)	
15	Vibration、 Ring	Compare with the sample customer supply		Compare with the sample customer supply when assemble		
16	Frequency Of FPC Bend	According to the use of product (main FPC of foldaway cell phone ≥6 thousand)			Measure instrument Bend angle : 150° PC in the casement when customer supply	

11 Handling Precautions

11.1 Mounting method

The LCD panel of Daxian LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

11.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent [recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl) , Salfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Salfur (S) from customer, Responsibility is on customer.

11.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

11.4 packing

- Module employ LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

11.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified

operation temperature.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

11.6 storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

11.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

12 Precaution for use

12.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

12.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to Daxian , and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

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13 Dimensional Outline

